

NOTES

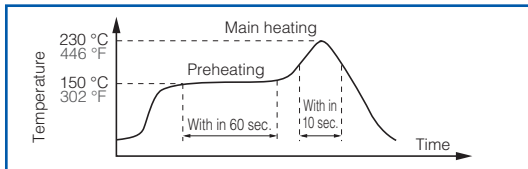
■ Mounting

Use the land of the printed-circuit board on which the sensor is securely fixed.

■ Soldering

Avoid the external thermal influence as the product has a limited thermal capacity due to its compact structure. Heat deformation may damage the sensor or deteriorate its performance. Use the non-corrosive rosin flux. Prevent the flux from entering into the inside of the product as the sensor is exposed to the atmosphere.

- 1) Manual soldering
 - Raise the temperature of the soldering tip between 260 and 300 °C 500 and 572 °F (30 W) and solder within 5 seconds.
 - The sensor output may vary if the load is applied on the terminal during soldering.
 - Keep the soldering tip clean.
- 2) DIP soldering (DIP Terminal)
 - Keep the temperature of the DIP solder tank below 260 °C 500 °F and solder within 5 seconds.
 - To avoid heat deformation, do not perform DIP soldering when mounting on the circuit board which has a small thermal capacity.
- 3) Reflow soldering (SMD Terminal)
 - The recommended reflow temperature profile conditions are given below.



- We recommend the screen solder printing method as the method of cream.
 - Please refer to the recommended PC board specification diagram for the PC board foot pattern.
 - Self alignment may not always work as expected, therefore, please carefully the position of the terminals and pattern.
 - The temperature of the profile is assumed to be a value measured with the printed wiring board of the terminal neighborhood.
 - Please evaluate solderability under the actual mounting conditions since welding and deformation of the pressure inlet port may occur due to heat stress depending on equipments or conditions.
- 4) Rework soldering
 - Complete rework at a time.
 - Use a flattened soldering tip when performing rework on the solder bridge. Do not add the flux.
 - Keep the soldering tip below the temperature described in the specifications.
 - 5) Avoid drop and rough handling as excessive force may deform the terminal and damage soldering characteristics.
 - 6) Keep the circuit board warpage within 0.05 mm of the full width of the sensor.
 - 7) After soldering, do not apply stress on the soldered part when cutting or bending the circuit board.
 - 8) Prevent human hands or metal pieces from contacting with the sensor terminal.
Such contact may cause anomalous outlets as the terminal is exposed to the atmosphere.

- 9) After soldering, prevent chemical agents from adhering to the sensor when applying coating to avoid insulation deterioration of the circuit board.
- 10) Please consult us concerning leadfree soldering.

■ Cleaning

- Prevent cleaning liquid from entering the inside of the product as the sensor is exposed to the atmosphere.
- Do not perform ultrasonic cleaning in order to prevent damages to the product.

■ Environment

- 1) Avoid use and storage in the corrosive gas (organic solvent, sulfurous acid and hydrogen sulfide gases) which negatively affects the product.
- 2) Avoid use in a place where these products come in contact with water as the sensor does not have a splash-proof construction.
- 3) Avoid use in an environment where these products cause dew condensation.
When water attached to the sensor chip freezes, the sensor output may be fluctuated or damaged.
- 4) Due to the structure of the pressure sensor chip, the output varies under light.
Do not expose the sensor chip to light when applying a voltage by using a transparent tube.
- 5) Do not apply high-frequency oscillation, such as ultrasonic waves, to the product.

■ Quality check under actual use conditions

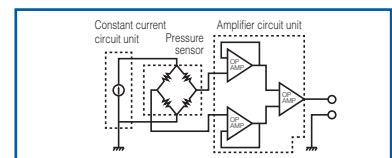
These specifications are for individual components. Before use, carefully check the performance and quality under actual use conditions to enhance stability.

■ Other precautions

- 1) The wrong mounting method and the pressure range may invite the risk of accidents.
- 2) Only applicable pressure medium is dry air. Avoid use in the corrosive gas (organic solvent, sulfurous acid and hydrogen sulfide gases) or other mediums containing moisture or foreign substances. Such mediums may damage or break the product.
- 3) The pressure sensor chip is located inside the pressure introduction port. Do not insert foreign substances, such as wires, into the port as those substances may damage the chip and close the port. Do not block the atmosphere introduction port.
- 4) Use electric power within the rated power range. Use beyond the range may damage the product.
- 5) Follow below instructions as static electricity may damage the product:
 - (1) For Storage, short the circuit between terminals by using conductive substances or wrap the whole chip with aluminum foil. For storage and transportation, avoid plastic containers which are easily electrified.
 - (2) Before use, connect electrified materials on desk and operators to the ground in order to safely discharge static electricity.
- 6) Carefully select and fix tubes, introduction pipes and products based on the working voltage. Please contact us for any inquires.

APPLICATION CIRCUIT DIAGRAM (EXAMPLE)

The pressure sensor converts a voltage by constant current drive and if necessary, amplifies the voltage. The circuit on the right is a typical use example.



MOUNTING METHOD

The general method of air pressure transmission varies depending on the low/high pressure condition.

• Usage note

- (1) Select a study pressure introduction pipe to avoid pressure leak.
- (2) Securely fix the pressure introduction pipe to avoid pressure leak.
- (3) Do not block the pressure introduction pipe.

Methods of transmitting air pressures

